

STTH12R06

Turbo 2 ultrafast high voltage rectifier

Features

- Ultrafast switching
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses
- Package insulation voltage: TO220AC ins: 2500 V_{RMS} TO-220FPAC: 2000 V_{DC}

Description

The STTH12R06 uses ST Turbo 2 600V technology and is specially suited as a boost diode in continuous mode power factor corrections and hard switching conditions.

This device is also intended for use as a free wheeling diode in power supplies and other power switching applications.

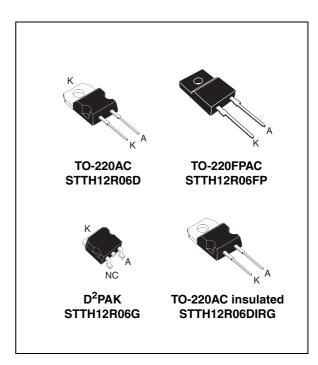


Table 1. Device summary

Symbol	Value
I _{F(AV)}	12 A
V_{RRM}	600 V
I _{RM} (typ)	7 A
T _j	175 °C
V _F (typ)	1.4 V
t _{rr} (max)	25 ns

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Table 2. Absolute ratings (limiting values)

Symbol		Parameter			
V_{RRM}	Repetitive peak reverse voltage	Repetitive peak reverse voltage			V
	Forward rms current	TO-220AC / TO-220F	TO-220AC / TO-220FPAC / D ² PAK		Α
I _F (RMS)	Polward IIIIs current	TO-220AC ins.		24	А
		TO-220AC / D ² PAK	T _c = 125 °C		
$I_{F(AV)}$	Average forward current $\delta = 0.5$	TO-220FPAC	T _c = 50 °C	12	Α
		TO-220AC ins.	T _c = 80 °C		
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$			100	Α
T _{stg}	Storage temperature range			-65 to + 175	°C
T _j	Maximum operating junction temperature			175	°C

Table 3. Thermal resistance

Symbol	Parameter		Value (max)	Unit
		TO-220AC / D ² PAK	1.7	
R _{th(j-c)}	Junction to case	TO-220FPAC	4.4	°C/W
		TO-220AC ins.	3.3	

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
	Reverse leakage current	T _j = 25 °C	V - V			45	μA
I _R	neverse leakage current	T _j = 125 °C	$V_R = V_{RRM}$		50	600	μΑ
V _F	Forward voltage drop	T _j = 25 °C	Ι = 12 Λ			2.9	V
VF	Forward voitage drop	$T_j = 125 ^{\circ}\text{C}$ $I_F = 12 \text{A}$			1.4	1.8	V

To evaluate the conduction losses use the following equation: P = 1.16 x $I_{F(AV)}$ + 0.053 $I_{F}^{2}_{(RMS)}$

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Table 5. Dynamic Characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit				
			$I_F = 0.5 \text{ A}, I_{rr} = 0.25 \text{ A},$ $I_R = 1 \text{ A}$			25					
t _{rr}	Reverse recovery time	T _j = 25 °C	$I_F = 1 \text{ A},$ $dI_F/dt = -50 \text{ A/}\mu\text{s},$ $V_R = 30 \text{ V}$			45	ns				
I _{RM}	Reverse recovery current				7.0	8.4	Α				
S factor	Softness factor	T _j = 125 °C	T _j = 125 °C	T _j = 125 °C	$T_j = 125 ^{\circ}\text{C}$	T _j = 125 °C	$T_j = 125 ^{\circ}\text{C}$ $I_F = 12 \text{A}, V_R = 400 \text{V},$ $dI_F/dt = -200 \text{A/}\mu\text{s}$		0.2		
Q _{rr}	Reverse recovery charges		Δ.ρ.σ. – 20070μο		180		nC				
t _{fr}	Forward recovery time	$I_F = 12 \text{ A}, dI_F/dt = 96$				200	ns				
V _{FP}	Forward recovery voltage	$T_j = 25 ^{\circ}\text{C}$ A/ μ s, $V_{FR} = 1.1 \text{x} V_{Fmax}$			5.5	V					

Figure 1. Conduction losses versus average current

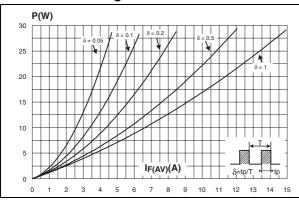


Figure 2. Forward voltage drop versus forward current

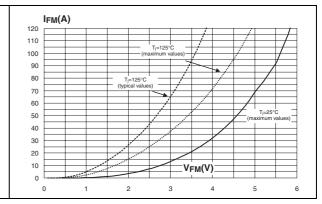
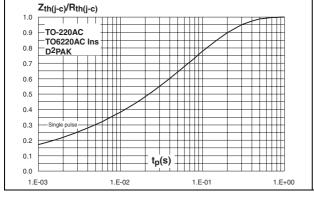
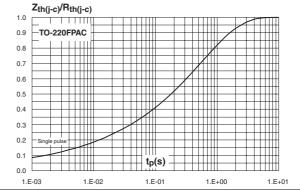


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

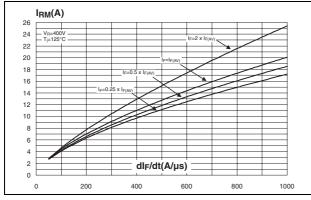




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Figure 5. Peak reverse recovery current versus dl_F/dt (typical values)

Figure 6. Reverse recovery time versus dl_F/dt (typical values)



t_{rr}(ns)

80

70

60

1<sub>[=2 × | [ε_(N))</sup>

1_{[=1 | [ε_(N))}

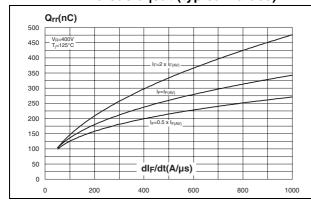
1_{[=0.5 × | [ε_(N))}

1_{[-1 | [ε_(N))}

1</sub>

Figure 7. Reverse recovery charges versus dl_E/dt (typical values)

Figure 8. Softness factor versus dl_F/dt (typical values)



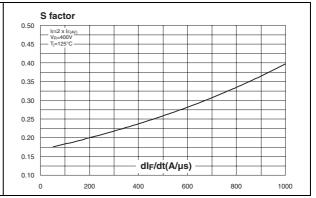
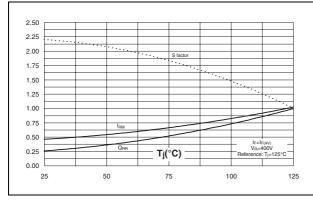
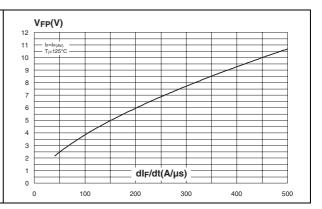


Figure 9. Relative variations of dynamic parameters versus junction temperature

Figure 10. Transient peak forward voltage versus dl_F/dt (typical values)



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Figure 11. Forward recovery time versus dl_F/dt (typical values)

Figure 12. Junction capacitance versus reverse voltage applied (typical values)

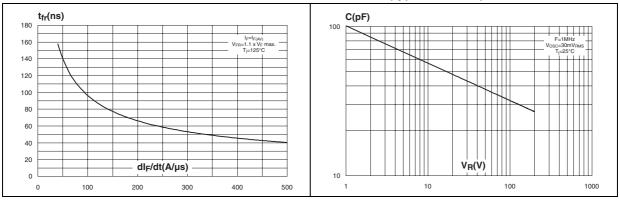
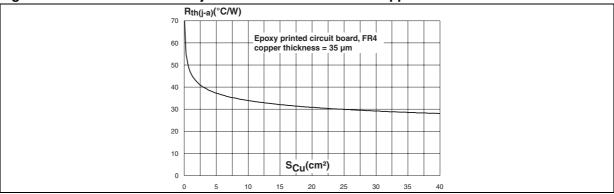


Figure 13. Thermal resistance junction to ambient versus copper surface under tab



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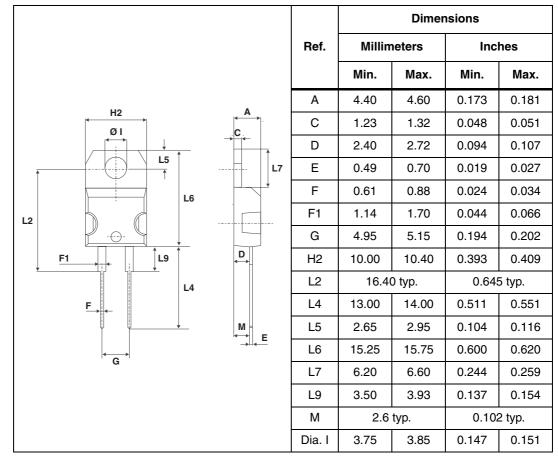
Epoxy meets UL94, V0

Cooling method: by conduction (C)

Recommended torque value: 0.4 to 0.6 N·m

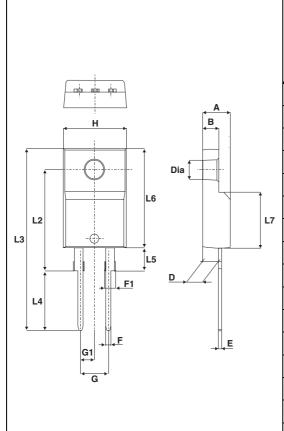
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 6. TO-220AC dimensions



STTH12R06 Package information

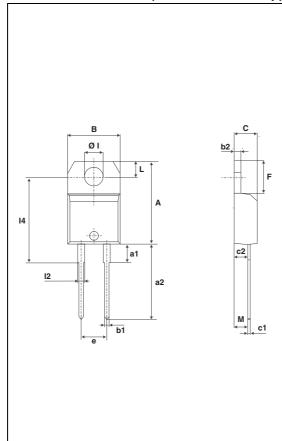
Table 7. TO-220FPAC dimensions



	Dimensions				
Ref.	Millin	Millimeters		hes	
	Min.	Max.	Min.	Max.	
Α	4.4	4.6	0.173	0.181	
В	2.5	2.7	0.098	0.106	
D	2.5	2.75	0.098	0.108	
Е	0.45	0.70	0.018	0.027	
F	0.75	1	0.030	0.039	
F1	1.15	1.70	0.045	0.067	
G	4.95	5.20	0.195	0.205	
G1	2.4	2.7	0.094	0.106	
Н	10	10.4	0.393	0.409	
L2	16	Тур.	0.63	Тур.	
L3	28.6	30.6	1.126	1.205	
L4	9.8	10.6	0.386	0.417	
L5	2.9	3.6	0.114	0.142	
L6	15.9	16.4	0.626	0.646	
L7	9.00	9.30	0.354	0.366	
Dia.	3.00	3.20	0.118	0.126	

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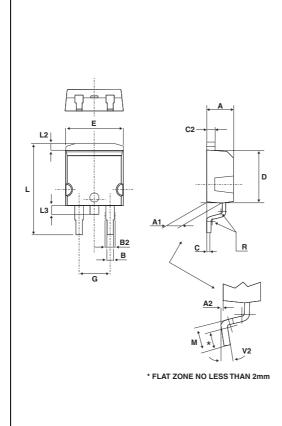
Table 8. TO-220AC (nins. and ins. 20-up) dimensions



	Dimensions					
Ref.	Millimeters				Inches	
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	15.20		15.90	0.598		0.625
a1		3.75			0.147	
a2	13.00		14.00	0.511		0.551
В	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
С	4.40		4.60	0.173		0.181
c1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
е	4.80		5.40	0.189		0.212
F	6.20		6.60	0.244		0.259
ØI	3.75		3.85	0.147		0.151
14	15.80	16.40	16.80	0.622	0.646	0.661
L	2.65		2.95	0.104		0.116
12	1.14		1.70	0.044		0.066
М		2.60			0.102	

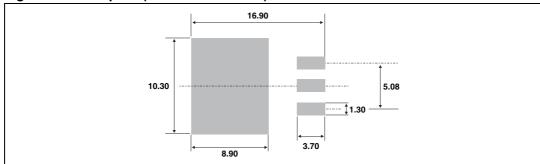
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Table 9. D²PAK dimensions



		Dimer	nsions	
Ref.	Millim	Millimeters		hes
	Min.	Max.	Min.	Max.
Α	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
В	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
С	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
Е	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
М	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016	6 typ.
V2	0°	8°	0°	8°

Figure 14. Footprint (dimensions in mm)



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Table 10. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH12R06D	STTH12R06D	TO-220AC	1.90 g	50	Tube
STTH12R06G	STTH12R06G	D ² PAK	1.48 g	50	Tube
STTH12R06G-TR	STTH12R06G	D ² PAK	1.48 g	1000	Tape and reel
STTH12R06FP	STTH12R06FP	TO-220FPAC	1.70 g	50	Tube
STTH12R06DIRG	STTH12R06DI	TO-220AC ins.	1.86 g	50	Tube

4 Revision history

Table 11. Document revision history

Date	Revision	vision Changes	
January-2002	1	Initial release.	
18-Oct-2004	2	D ² PAK and TO-220AC insulated packages added	
10-Aug-2006	3	Reformatted to current standards. Added package insulation voltages on page 1	
15-Feb-2010	4	Corrected typographical error in order codes in <i>Table 10</i> .	

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